

WHAT IS CLAIMED IS:

1. A packing structure of an electronic device comprising:
  - a frame having a package area where said electronic device is disposed therein;
  - 5 an insulating block disposed on one side of said package area and connected to said frame; and
  - a plurality of frame leads aligned in parallel and connected to said insulating block and said electronic device.
2. The packing structure according to claim 1, wherein said electronic
- 10 device is a coil.
3. The packing structure according to claim 1, wherein said frame is made of metal.
4. The packing structure according to claim 1, wherein said package area is disposed in the center of said frame and in a shape of a rectangle.
- 15 5. The packing structure according to claim 1, wherein said insulating block is formed by a plastic molding process.
6. The packing structure according to claim 1, wherein said plurality of frame leads are insulated with each other.
7. The packing structure according to claim 1, wherein said plurality of
- 20 frame leads are connected to said electronic device through a plurality of wires.
8. The packing structure according to claim 1, wherein each of said plurality of frame leads has one end turned upwardly by about 90 degrees and embedded in said insulating block.
- 25 9. A packing structure of an electronic device comprising:
  - a frame having a package area where said electronic device is disposed therein;

an insulating block disposed on one side of said package area and connected to said frame; and

a plurality of frame leads aligned in parallel and insulated with each other, each of said frame leads having one end embedded in said insulating block and the other end connected to said electronic device by a corresponding wire.

10. A method for packing an electronic device comprising steps of:

providing a frame having a package area where said electronic device is disposed therein, a connecting arm and a plurality of frame leads which are connected to the connecting arm;

forming an insulating block on one side of said package area;

interconnecting said frame and said plurality of frame leads with said insulating block;

partially cutting said connecting arm to insulate said plurality of frame leads against each other; and

electrically connecting said electronic device to said plurality of frame leads.

11. The method according to claim 10, wherein said electronic device is a coil.

12. The method according to claim 10, wherein said frame is made of metal.

13. The method according to claim 10, wherein said package area is disposed in the center of said frame and in a shape of a rectangle.

14. The method according to claim 10, wherein said insulating block is formed by a plastic molding process.

15. The method according to claim 10, wherein said plurality of frame leads are connected to said electronic device through a plurality of wires.